AI Technology, Inc (AIT) To Attend and Present Paper at IWLPC. AIT also attending IPC/SMTA High-Reliability Cleaning and Conformal Coating Conference.

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AIT Technology, Inc. (AIT) is proud to announce that it will be attending two conferences this November.

The first conference AIT will be attending is the International Wafer-Level Packaging Conference (IWLPC), November 11-12 at the Double Tree Hotel in San Jose, CA. This year, AIT’s own Dr. Frederick Lo will be presenting his paper, Recent Advances in Die Attach Film.

Be sure to listen to this fascinating talk and visit AIT at booth 43.

Dr. Lo’s paper discusses the advantages of using die attach film at the wafer level compared to using die attach material on individual die. To completely take advantage of the use of die attach film at the wafer level, the die attach film has to be optimized to account for various process conditions that the film has to successfully pass through without degradation in any of its end use properties of adhesion strength and thermal and electrical properties.

More recently, the demand for hand held devices has led to more advanced technologies in 2.5D and 3D packaging and in the handling of extremely thin wafers and dies. The material supply industry has responded in providing newer generations of die attach films and wafer protection material to these increasingly demanding challenges.

Throughout the paper Dr. Lo examines the criteria for higher efficiency, more reliability and higher performance die-attach film at the wafer level. Additionally, attention is given to the effects of interconnection from chip to package on the choice of die-attach solutions. The packaging using wire-bonding, flip-chip soldering or the direct mechanical contact attach from flip-chip to bond pads effectively dictates the choice of different wafer level die-attach solutions.

The second conference AIT will be attending is the IPC/SMTA High-Reliability Cleaning and Conformal Coating Conference, Nov 18-20 in Schaumburg, Illinois. AIT is especially excited to attend and showcase its improved Prima Protect Coatings. We look forward to discussing your unique coating needs!

Plus, just in time for the High-Reliability Cleaning and Conformal Coating Conference, AIT has produced a Conformal Coating Video!
About AI Technology, Inc. (AIT):

Since pioneering the use of flexible epoxy technology for microelectronic packaging in 1985, AI Technology, Inc. (AIT) has been one of the leading forces in development and patented applications of advanced materials and adhesive solutions for electronic interconnection and packaging. AI Technology, Inc. (AIT) offers some of the most reliable adhesives and underfills for die bonding for the largest dies, stack-chip packaging with dicing die-attach film (DDAF), flip-chip bonding and underfilling and high temperature die bonding for single and multiple-chip modules for applications beyond 230°C. The company continues to provide the best adhesive solution for component and substrate bonding for both military and commercial applications. AIT’s thermal interface material solutions, including our patented phase-change thermal pads, thermal greases and gels and thermal adhesives have set many bench marks of performance and reliability for power semiconductors, modules, computers and communication electronics.

For an application analysis: http://www.aitechnology.com/analysis/

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